

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HSIU WEN HSU	11/24/2011
CHIH CHENG HSIEH	11/24/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NIKO SEMICONDUCTOR CO., LTD.
<b>Street Address:</b>	12F., NO. 368, GONGJIAN RD., XIZHI DIST.
<b>City:</b>	NEW TAIPEI CITY
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	221
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13305771
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	100P000044US
<b>NAME OF SUBMITTER:</b>	ZHUO XU
<b>Total Attachments: 1</b> source=10044Assignment#page1.tif	

CH \$40.00 13305771

ASSIGNMENT DEED

This Assignment agreement is applicable to an invention entitled (invention Title) SEMICONDUCTOR STRUCTURE WITH LOW RESISTANCE OF SUBSTRATE AND LOW POWER CONSUMPTION

The PATENT RIGHTS referred to in this agreement are:

- (Check one) [X] a Patent Application for this invention, executed by the ASSIGNOR(s) concurrently with this Assignment
[ ] U.S. Patent Application Serial No. \_\_\_\_\_, filed \_\_\_\_\_
[ ] U.S. Patent No. \_\_\_\_\_, issued \_\_\_\_\_

The PATENT RIGHTS assigned under this agreement are:

- (Check one) [X] U.S. Patent rights only
[ ] worldwide Patent rights. In this case, the Assignee shall have the right to claim the benefit of the filing date of any U.S. Patent Application identified above.

The ASSIGNOR(s) referred to in this agreement is (or are):

(Full name of sole or first inventor) HSIU WEN HSU (FAMILY NAME: HSU)
(Address) No. 15, Alley 7, Lane 197, Shangren St., Xinfeng Shiang, Hsinchu County 304, Taiwan, R.O.C.

(Full name of second joint inventor, if any) CHIH CHENG HSIEH (FAMILY NAME: HSIEH)
(Address) No. 1, Aly. 16, Ln. 50, Longqing St., Zhongli City, Taoyuan County 320, Taiwan, R.O.C.

(Full name of third joint inventor, if any) \_\_\_\_\_
(Address) \_\_\_\_\_

(Full name of fourth joint inventor, if any) \_\_\_\_\_
(Address) \_\_\_\_\_

The First ASSIGNEE referred to in this agreement is:

(Name of Assignee) NIKO SEMICONDUCTOR CO., LTD.
(Address of Assignee) 12F, No.368, Gongjian Rd., Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)

The Second ASSIGNEE referred to in this agreement is:

(Name of Assignee) \_\_\_\_\_
(Address of Assignee) \_\_\_\_\_

The First ASSIGNEE is:

- (Check one) [ ] an individual
[ ] a partnership
[X] a Corporation of TAIWAN, R.O.C.
(State of Country)

The Second ASSIGNEE is:

- (Check one) [ ] an individual
[ ] a partnership
[ ] a Corporation of \_\_\_\_\_
(State of Country)

The ASSIGNOR(S), in consideration of \$ 1.00 paid by each ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE; their successors and assigns:

- the full and exclusive right to the invention;
an equal interest in and to the entire right, title and interest in and to the PATENT RIGHTS in the invention, all continuations, continuations-in-part, divisionals, re-issues, and re-examination patents and patent applications; and
the right to claim priority under 35 U.S.C. 119, based on any earlier foreign applications for this invention.

As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(s) hereby authorize(s) and requests the Director of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(s) as the ASSIGNEE(s) of an equal interest in the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE(s), their successors and assigns.

Further, the ASSIGNOR(s) agree(s) to communicate to said ASSIGNEE(s), or their representatives, any facts known to the ASSIGNOR(s) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuations-in-part, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(s), make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE(s), their successors and assigns, to obtain and enforce proper protection for said invention.

*Hsiu-wen Hsu*

HSIU WEN HSU (FAMILY NAME: HSU)

NOV. 24, 2011

(Signature of sole or first inventor)

(Date)

*Chih Cheng Hsieh*

CHIH CHENG HSIEH (FAMILY NAME: HSIEH)

NOV. 24, 2011

(Signature of second inventor, if any)

(Date)

(Signature of third inventor, if any)

(Date)

(Signature of fourth inventor, if any)

(Date)

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